

For immediate release

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NEXX Systems Sells Apollo for Image Sensor production to Leading Chinese Wafer Bumping Facility

Billerica, MA, USA – July 14, 2010 – NEXX Systems– a leading provider of advanced wafer-level chip scale packaging equipment, headquartered in the Boston area – today announced a repeat sputter tool order for an Apollo physical vapor deposition system to an emerging leader in flip chip manufacturing at their wafer bumping facility in China. The Apollo physical vapor deposition system will be used for wafer-level packaging of licensed CMOS image sensor technology. The Chinese outsourced assembly and test fab selected the Apollo based on its capabilities for superior temperature control, high throughput and exceptional via coverage. Through this sale, NEXX has expanded our installed base in image sensor technology to include some of the key players in CMOS image sensor technology and production.

About Apollo/Stratus Product Families: The Apollo advanced sputter deposition system incorporates multi-wafer processing commonly used in cluster tools while avoiding the disadvantages of central handling. The Apollo, specifically designed for wafer level packaging offers faster, more economical PVD processing. A significant advantage is the tool's processing flexibility: For example, it can produce CMOS image sensors as well as flip chip bumps.

Stratus provides industry-leading yield at what we believe is the lowest CoO for pattern plating and TSV applications. NEXX Systems' AquaTorr™, an advanced prewet system, enables high aspect ratio, void-free copper fill for TSVs. Innovative ShearPlate™ technology provides exceptional process with excellent across wafer uniformity and alloy composition.

About NEXX: NEXX Systems brings exceptional technical expertise to the flip chip and advanced packaging markets. Our product lines provide the most efficient, yet affordable, systems of their kind: Apollo for multi-layer sputter deposition of metals, and Stratus for high throughput electro-deposition of metals. Additional information can be found at: www.nexxsystems.com.